



SOT633-3

plastic thermal enhanced thin shrink small outline package;
38 leads; body width 6.1 mm; lead pitch 0.65 mm; exposed
die pad

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HTSSOP38
Package type industry code	HTSSOP38
Package style descriptive code	HTSSOP (thermal enhanced thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	22-1-2004

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		12.4	-	12.5	12.6	mm
E	package width		6	-	6.1	6.2	mm
A	seated height		[tbd]	-	1.2	1.2	mm
A ₂	package height		0.8	-	0.9	1.05	mm
n ₂	actual quantity of termination		-	-	38	-	



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2. Package outline

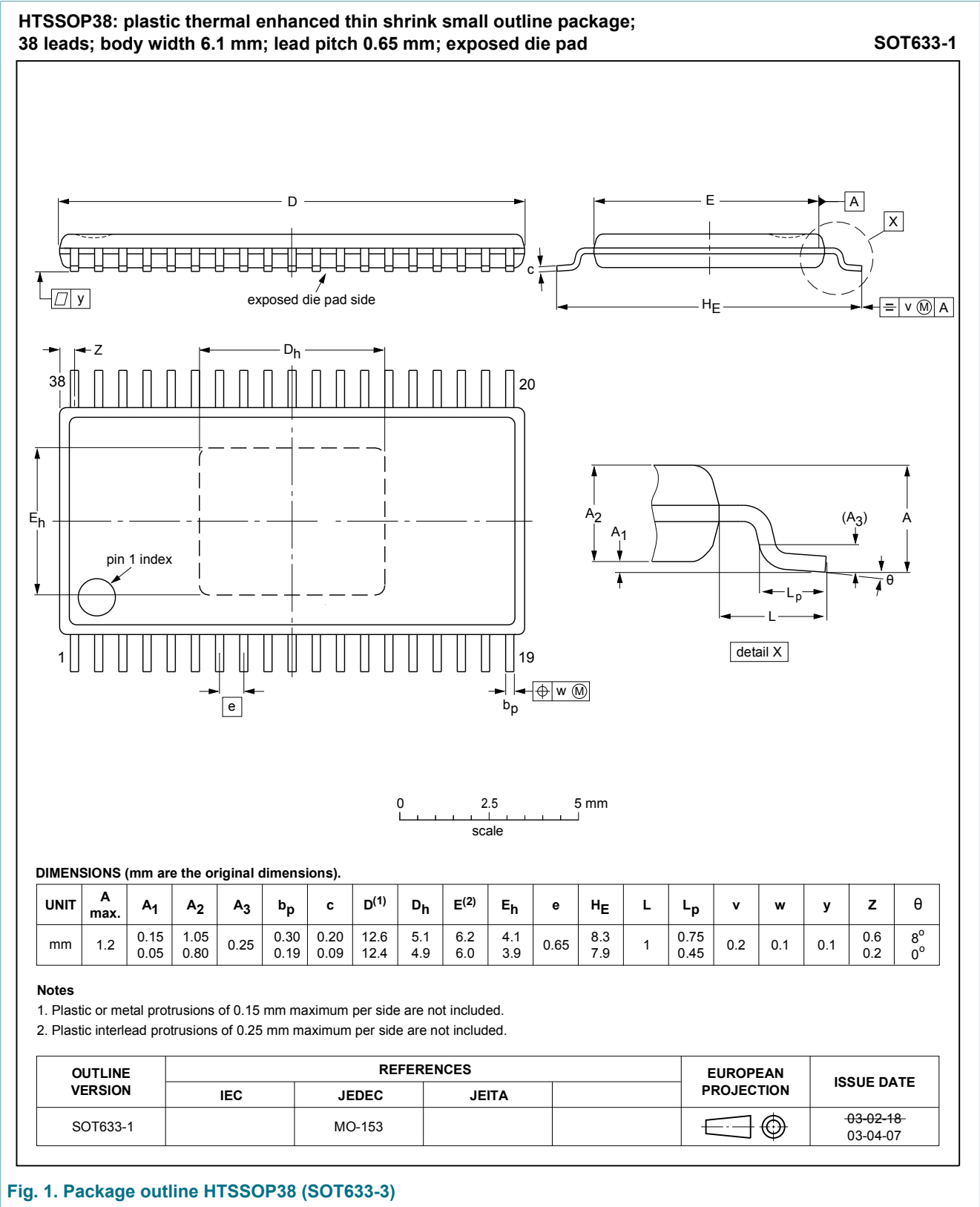


Fig. 1. Package outline HTSSOP38 (SOT633-3)

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3. Soldering

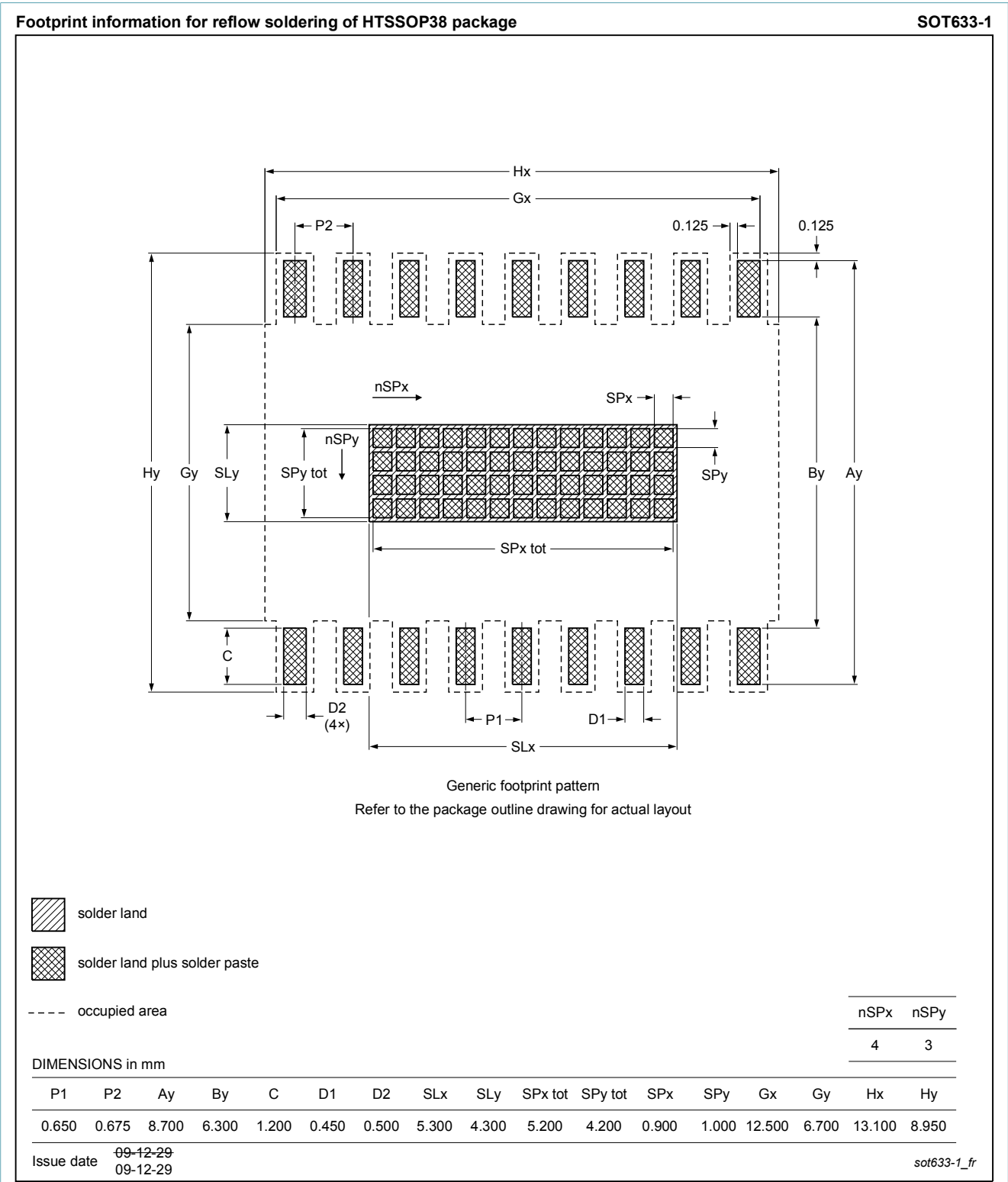


Fig. 2. Reflow soldering footprint for HTSSOP38 (SOT633-3)

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4. Legal information

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